

Due Date August 19, 2006

OSMM&N File No. 288839US0PCT

By NFO/atw/FF

Serial No. New U.S. PCT Application based on PCT/EP04/53669

In the matter of the Application of Ekkehard MUEH, et al.

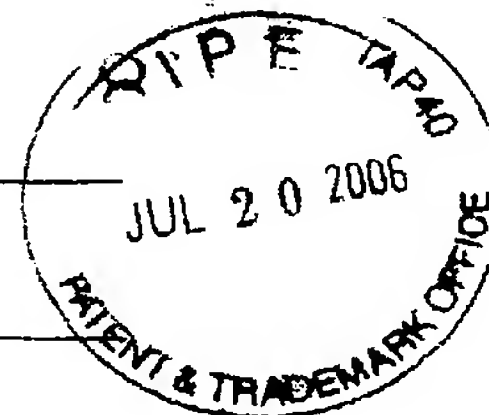
For SILICON COMPOUNDS FOR PRODUCING SiO₂-CONTAINING
INSULATING LAYERS ON CHIPS

The following has been received in the U.S. Patent Office on the date stamped hereon:

- Combined Declaration, Petition & Power of Attorney (4 pages)
- Application Data Sheet (3 pages)
- Notice of Priority
- Dep. Acct. Order Form
- Credit Card Payment Form for \$1,000.00
- PCT Transmittal Letter
- Preliminary Amendment
- PCT/IB/304
- Information Disclosure Statement
- PTO-1449
- List of Related Cases

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